

Course Title: Electronic Packaging

Course Code: EEA 123

Course Background / Summary:

This course is designed and focused on the fundamentals of electronic packaging theory/concepts and how electronic packaging is designed and manufactured. Among the topics covered are an introduction to electronic packaging, materials in electronic packaging, package and board assembly, electronic packaging components, equipment and processes, and quality and reliability (Q&R) in electronic packaging.

Course Objectives:

- Understand the fundamentals of electronic packaging.
- Understand electronic packaging developments and manufacturing processes.
- Familiarize with the materials in electronic packaging.

Target Audience:

- Industrial workers from engineers to senior engineers, managers, etc.
- Teaching staff (vocational & technical teachers), lecturers, etc.

Course Duration: 3 Days

Course Contents

1.0 Introduction to Electronic Packaging

2.0 Overview of Materials in Electronic Packaging

3.0 IC Package Assembly and Board Assembly

4.0 Quality and Reliability in Electronic Packaging

5.0 Interconnect Technology and Materials

6.0 Polymer Materials for Electronic Packaging

7.0 Thermals

8.0 Substrates

9.0 Materials Characterization